









# PRODUCT DATASHEET

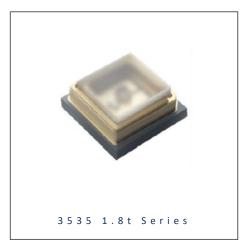




- ► Ceramic High Power
- ➤ 3535 1.8t Series
- ► UV (275nm)

N0Q52S93Z





# **3535 1.8t Series**





Release Date: 24 September 2020 Version: A1.0

## **FEATURES:**

Package: Ceramic SMT Package with Glass Lens

Forward Current: 100mA Forward Voltage (typ.): 6.1V

Radiant Power (typ.): 8.5mW@100mA

Colour: Ultraviolet (UV) Wavelength: 275nm Viewing angle: 120°

Materials:

Die: InGaN

Resin: Glass (Water Clear)

L/F: Ceramic

Operating Temperature: -10~+60°C Storage Temperature: -10~+65°C

**Grouping parameters:** 

Forward Voltage

**Radiant Power** 

Peak Wavelength

Soldering methods: IR Reflow soldering

MSL: Level 3 according to J-STD020

Packing: 12mm tape with min. 100pcs/reel, ø180mm (7")

## **APPLICATIONS:**

- **Industrial Curing**
- Counterfeit Detection
- **Medical Device**
- Fluorochemistry
- **Bacterial Identification**
- Cosmetology
- Magnetic Particle Inspection
- Clean Room Inspection
- Mineralogy







## **CHARACTERISTICS:**

## Absolute Maximum Characteristics (Ta=25°C)

Parameter	Symbol	Ratings	Unit
Maximum Forward Current	I <sub>MAX</sub>	150	mA
Pulse Current Width=100μs Duty 1/10	l <sub>P</sub>	180	mA
Junction Temperature	Tj	100	°C
Power Dissipation	R <sub>D</sub>	1.08	W
Operating Temperature	TOPR	-10~+60	°C
Storage Temperature	T <sub>STG</sub>	-10~+65	°C
Solder Temperature	T <sub>SOL</sub>	260 for 10sec	°C

## Electrical & Optical Characteristics (Ta=25°C)

Darameter	Symbol	Values			Unit	Test
Parameter		Min.	Тур.	Max.	Unit	Condition
Forward Voltage	VF		6.1		V	I <sub>F</sub> =100mA
Radiant Power	Po		8.5		mW	I <sub>F</sub> =100mA
Peak Wavelength	W <sub>P</sub>		275		nm	I <sub>F</sub> =100mA
Spectrum Half Width	Δλ		10		nm	I <sub>F</sub> =100mA
Viewing Angle	2θ <sub>1/2</sub>		120		deg	I <sub>F</sub> =100mA

<sup>1.</sup> Radiant Power ( $P_0$ )  $\pm 10\%$ , Forward Voltage ( $V_F$ )  $\pm 0.2V$ , Wavelength (nm)  $\pm 2$ nm

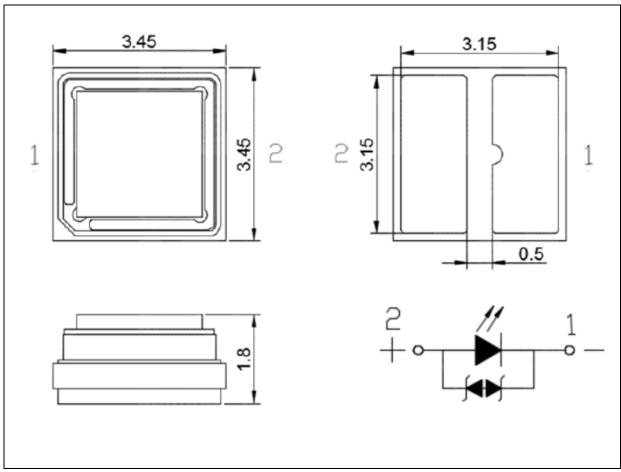






## **OUTLINE DIMENSION:**

## Package Dimension:



- 1. All dimensions are in millimetre (mm).
- 2. Tolerance ±0.13mm, unless otherwise noted.

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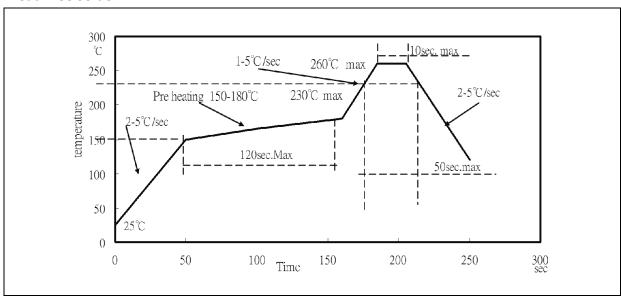






## **RECOMMENDED SOLDERING PROFILE:**

#### Lead-free Solder:



#### Note:

- 1. Maximum reflow soldering: 2 times.
- 2. Recommended reflow temperature 240°C. Maximum soldering temperature should be limited to 260°C.
- 3. Before, during, and after soldering, should not apply stress on the components and PCB board.

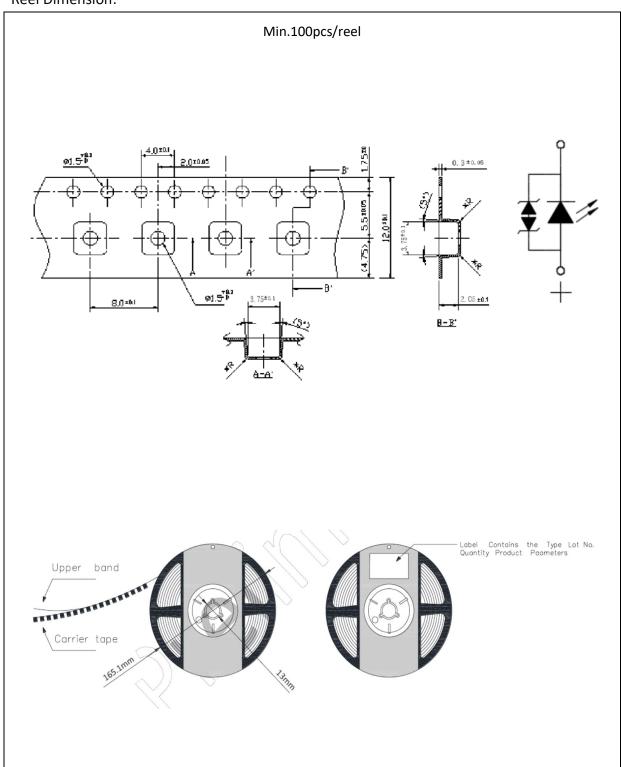






## **PACKING SPECIFICATION:**

## Reel Dimension:









#### PRECAUTIONS OF USE:

## Storage:

It is recommended to store the products in the following conditions:

- Humidity: 60% R.H. Max.
- Temperature: 5°C~30°C (41°F ~86°F).

Shelf life in sealed bag: 12 months at 5°C~30°C and <60% R.H.

Once the package is opened, the products should be used within a week. Otherwise, they should be kept in a damp-proof box with descanting agent <10% R.H. and apply baking before use.

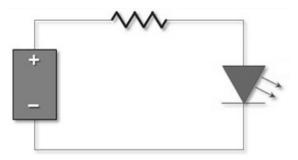
#### Baking:

It is recommended to bake the LED before soldering if the pack has been unsealed for longer than 24hrs. The suggested baking conditions are as followings:

• 65±3°C x 12hrs and <5%RH, taped / reel package.

It's normal to see slight color fading of carrier (light yellow) after baking in process.

## **Testing Circuit:**



Must apply resistor(s) for protection (over current proof).

## Cleaning:

Use alcohol-based cleaning solvents such as isopropyl alcohol to clean the LED carrier / package. Avoid putting any stress force directly on to the LED lens.

## ESD (Electrostatic Discharge):

Static Electricity or power surge will damage the LED. Use of a conductive wrist band or anti-electrosatic glove is recommended when handing the LED all time. All devices, equipment, machinery, work tables, and storage racks must be properly grounded.

In the events of manual working in process, make sure the devices are well protected from ESD at any time.







## **REVISION RECORD:**

Version	Date	Summary of Revision
A1.0	24/09/2020	Datasheet set-up.